Information for Lot 9 of ErP (Ecodesign)

This addendum addresses European Union (EU) Ecodesign requirements for servers and storage products. All data and ratings within this addendum are in reference only to the Supermicro product(s) in the manual. The below information conforms with requirements laid down in Annex II of the Commission Regulation 2019/424.

3(1)(a): See Section 1.1 of the system manual for the product type.

3(1)(b): See the title page and preface of the system manual for the trademark and manufacturer's address.

3(1)(c): See the title page of the system manual for product model number(s).

3(1)(d): See the serial number on the physical system to determine the year of manufacture.

3(1)(e-j): **PSU Efficiency and Power Factor Value (Table) (From 80 Plus report)**

PSU Model #: PWS-2K63A-1R **Watts:** 2600	**PSU Efficiency**				**Power Factor**
% of Rated Load	**10 %**	**20 %**	**50 %**	**100 %**	**50 %**
Single Output (AC-DC)	93.52%	96.03%	96.21%	94.25%	0.99

System (EUT) Efficiency in Idle State Power (Table)

Representative Configurations	**Measured Idle State Power (W)**	**Calculated Idle Power Allowance (W)**
High-End Performance Configuration	673.8	691.2
Low-End Performance Configuration	197.3	237.9

System (EUT) Efficiency in Active State Power (Table)

Representative Configurations	**Active State Efficiency Score (Effserver)**	**Minimum Active State Efficiency for 2-Socket Server**
High-End Performance Configuration	14.8	8.0
Low-End Performance Configuration	16.7	

3(1)(k): The operating condition class is **A2**.

	Dry bulb temp °C		Humidity range (non-condensing)			
Operating condition class	**Allowable range**	**Recommended range**	**Allowable range Dew Point (DP) Relative Humidity (RH)**	**Recommended range**	**Max dew point (°C)**	**Maximum rate of change (°C/hr)**
A1	15- 32	18-27	– 12 °C DP and 8 % RH to 17 °C DP and 80 % RH	– 9 °C DP to 15 °C DP and 60 % RH	17	5/20
A2	10-35	18-27	– 12 °C DP and 8 % RH to 21 °C DP and 80 % RH	Same as A1	21	5/20
A3	5-40	18-27	– 12 °C DP and 8 % RH to 24 °C DP and 85 % RH	Same as A1	24	5/20
A4	5-45	18-27	– 12 °C DP and 8 % RH to 24 °C DP and 90 % RH	Same as A1	24	5/20

3(1)(l): The idle state power at the higher boundary temperature of the operating conditions class is 1,347.6 W.

3(1)(m): The active state efficiency and performance is 14.8.

3(1)(n): There are two methods by which a user can securely delete data from this system. The user performing secure data deletion should be an IT professional.

The first is with a Unified Extensible Firmware Interface (UEFI) shell utility. This utility works on X10/X11/H11/H12/M11 motherboard series with onboard SATA/NVMe devices. Any user may access and download this utility through following link: https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9_Secure_Data_Deletion_Utility/

Download the shell utility package and extract it to a USB flash drive, then plug the drive into the server for which secure data deletion is necessary. Then turn the system on. Navigate to the BIOS setup menu, then place the server system into the UEFI shell environment. Follow the instructions in the README file to invoke the utility and complete the deletion.

The second method is through the secure data deletion tool provided by the original manufacturer of the hard drive. This should be used in a scenario where the shell utility is not applicable. Each manufacturer should have the tool available on their website. If needed, please look on the hard drive label for the name of the manufacturer and model information.

3(1)(o): List of recommended combinations of blade servers with chassis: N/A.

3(1)(p): List of all current SKUs within this product family: SSG-6049SP-DE1CR90.

3(3)(a): There is no use of cobalt in batteries in this product.

The indicative weight range of neodymium in the HDD is 0.0 if manufactured by Western Digital, and is between 5-25 grams if manufactured by Seagate.

3(3)(b): Please see the disassembly instructions on the next page.

Illustrated System Disassembly Instructions

Please note: All the illustrations in the below disassembly instructions are for demonstration only. Components shown here may not match exactly with the components in your system.

CAUTION: Always power off the system and unplug the power cord(s) first before disassembling the system!

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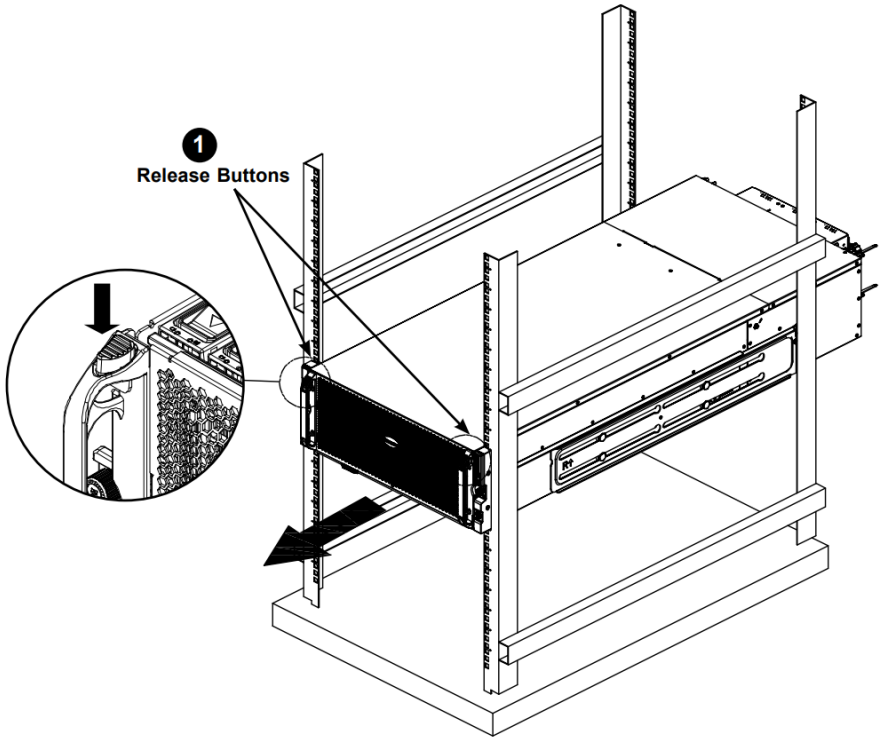
1. Data Storage Devices

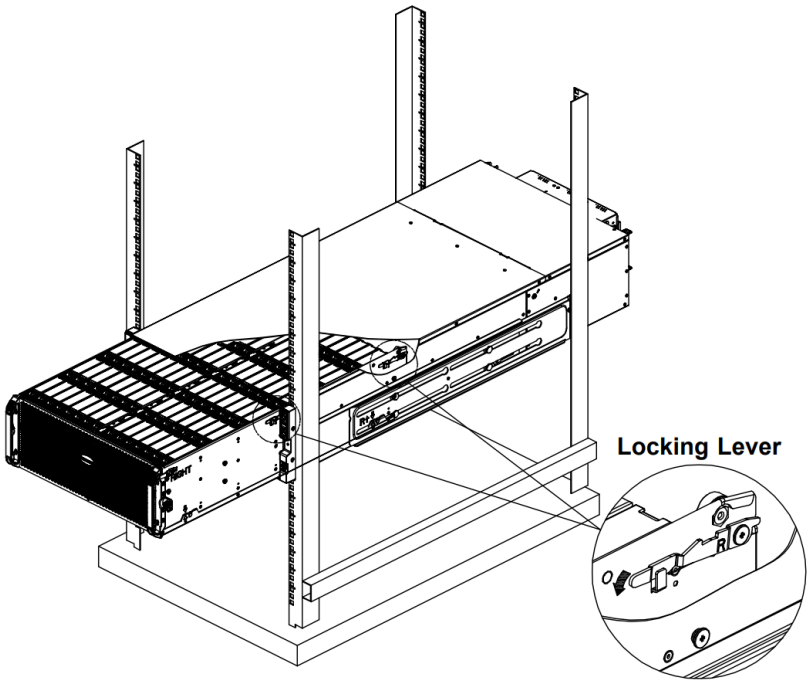
Type and number of fastenings: One (1) button and one (1) lever on each side of drawer.

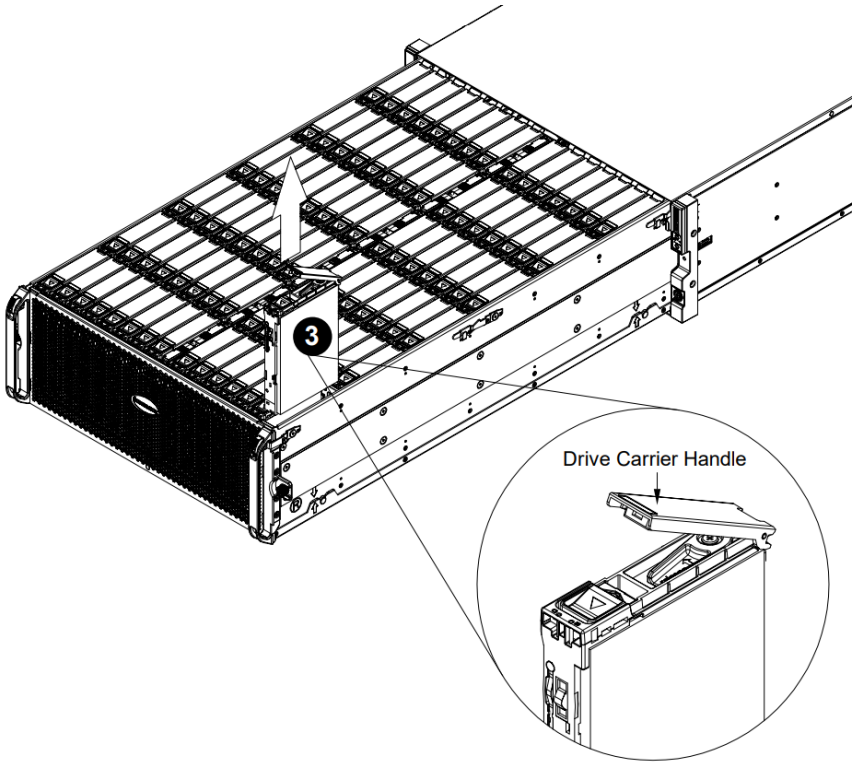
Tools required: None.

Procedure:

1. Press the release buttons on both of the front handles downward simultaneously, and pull the drive drawer handles forward from the rack.
2. Pull open the chassis so that a locking lever on each side of the chassis aligns with the front of the chassis cover and front of the rack, then press the lever down on each side to lock the open part of the chassis in place.
3. To load or remove hard drives and their carriers in the chassis, press their release buttons to eject their handles, and then pull the drives out by the handles.




Locking Lever

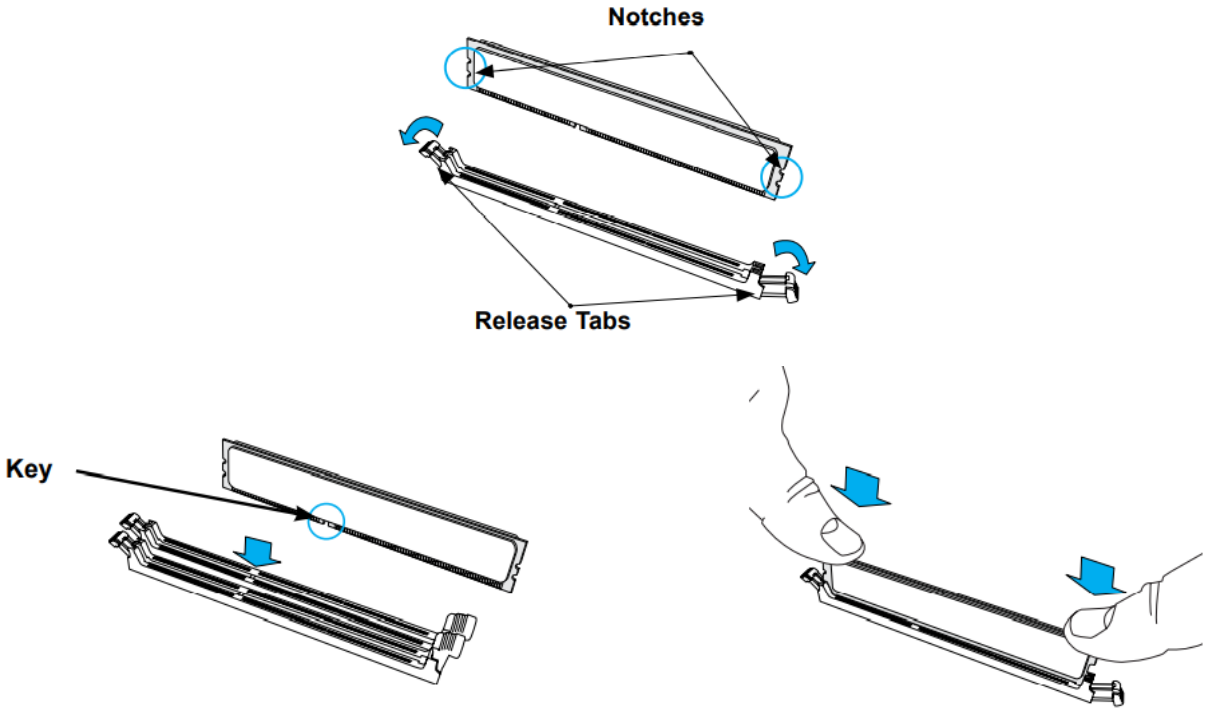

3
Drive Carrier Handle

4. Memory

Type and number of fastenings: Two (2) latches per memory module.

Tools required: None.

Procedure: Push the release tabs outward on both ends of the memory module slot to unlock it. Align the key of the module with the receptive point on the memory slot, and with your thumbs on both ends of the module, press the module straight down into the slot until it snaps into place. Press the release tabs to the locked position to secure the module into the slot.



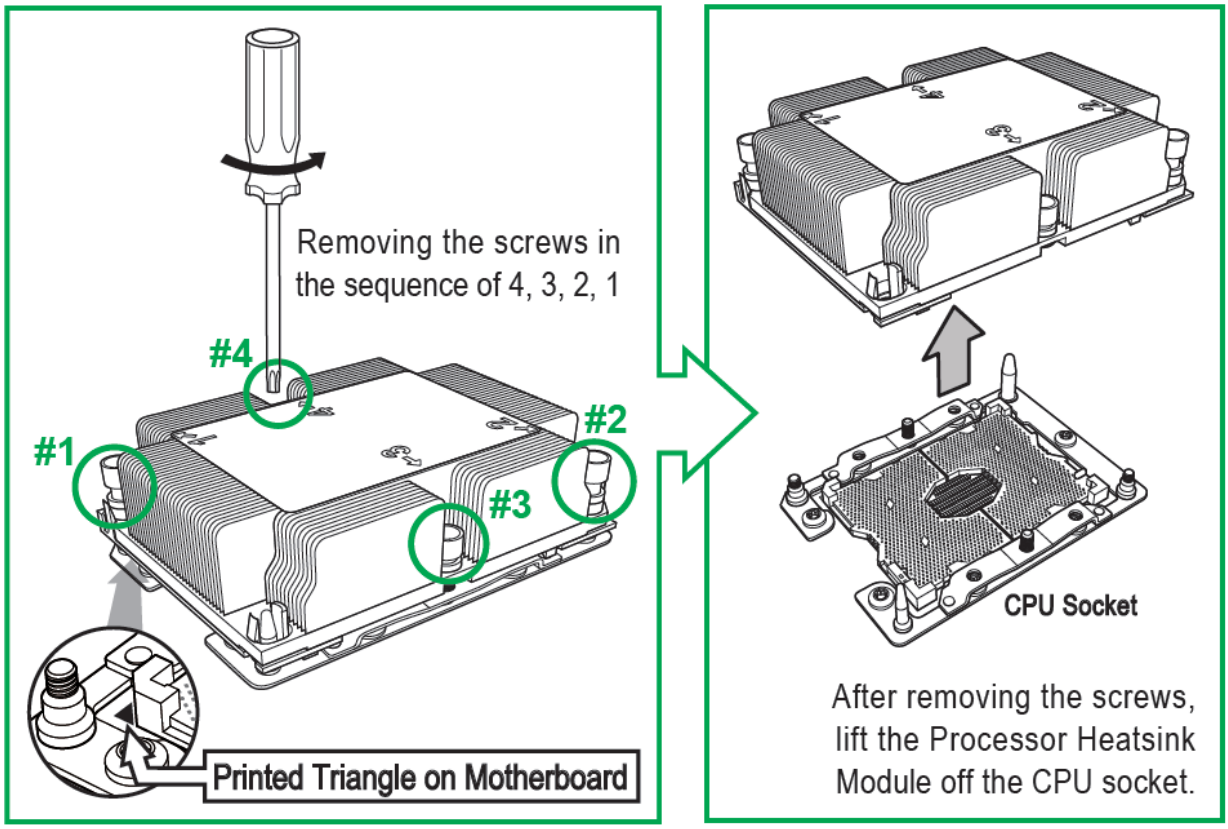
5. Processor

Type and number of fastenings: Four (4) T30 Torx screws.

Tools required: Screwdriver with T30 Torx bit.

Procedure: Using a T30 Torx-bit screwdriver, turn the screws on the processor heatsink module counterclockwise to loosen them from the socket, starting with screw marked #4, in the

sequence of 4, 3, 2, 1. After all four screws are removed, wiggle the processor heatsink module gently and pull it up to remove it from the socket.



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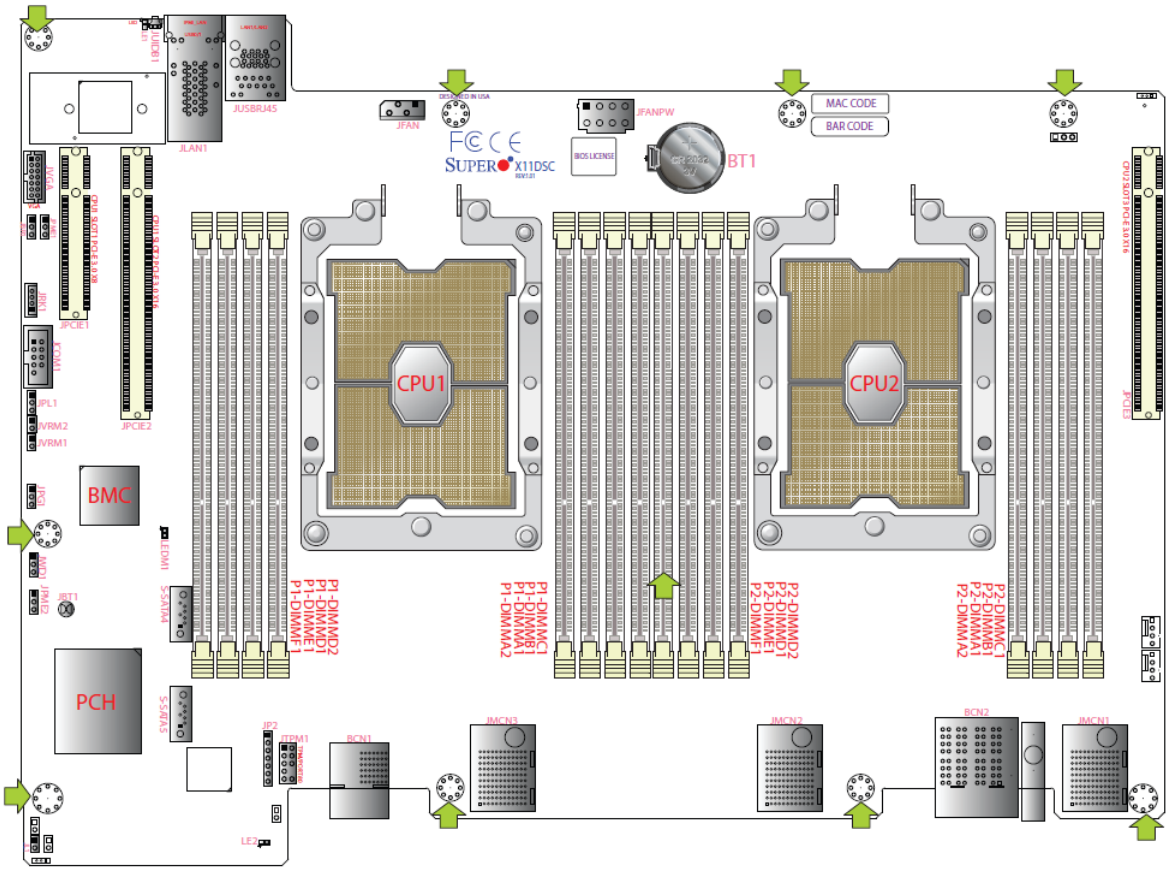
6. Motherboard

Type and number of fastenings: Nine (9) Phillips screws.

Tools required: Screwdriver with PH2 bit.

Procedure: Remove all nine Phillips screws. Lift the motherboard from its base.



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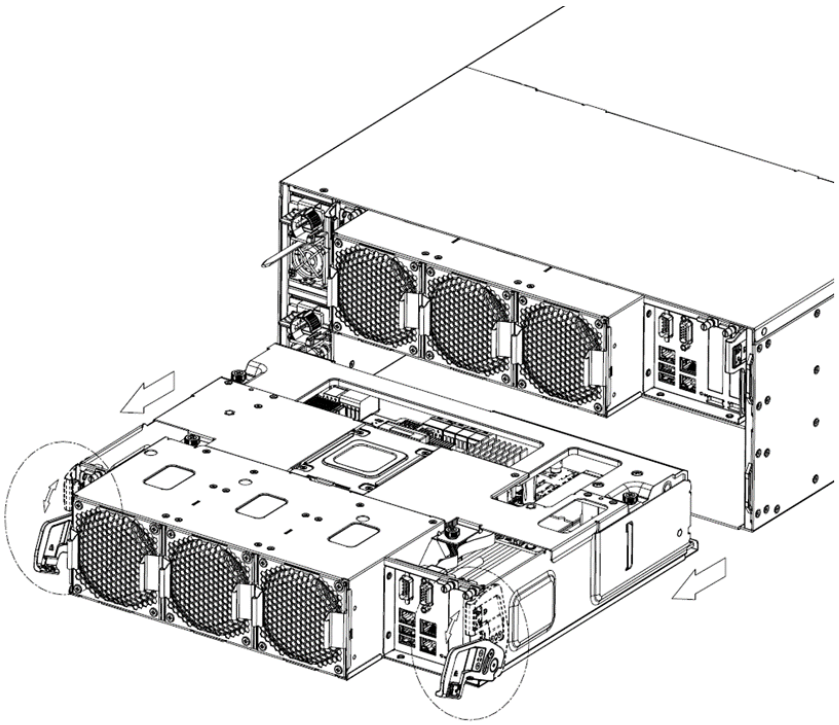
7. PCI-E Cards

Type and number of fastenings: Two (2) locking levers on each node. One (1) twist screw on each slot plate.

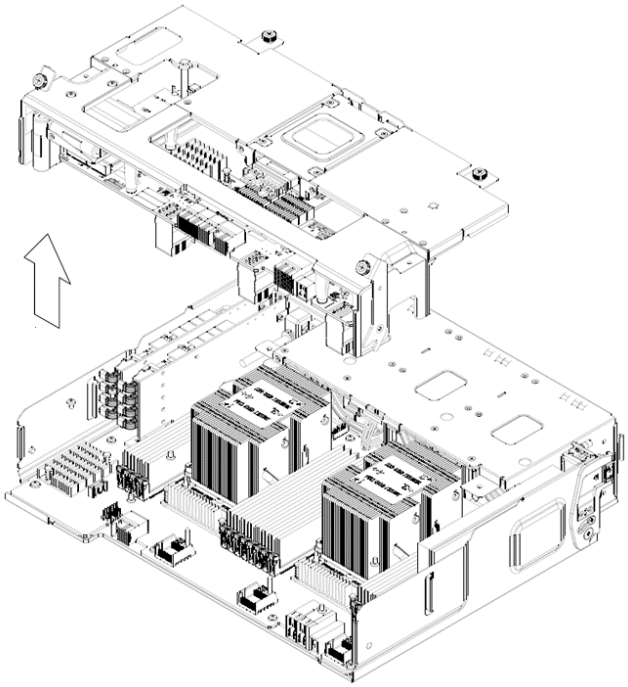
Tools required: None.

Procedure:

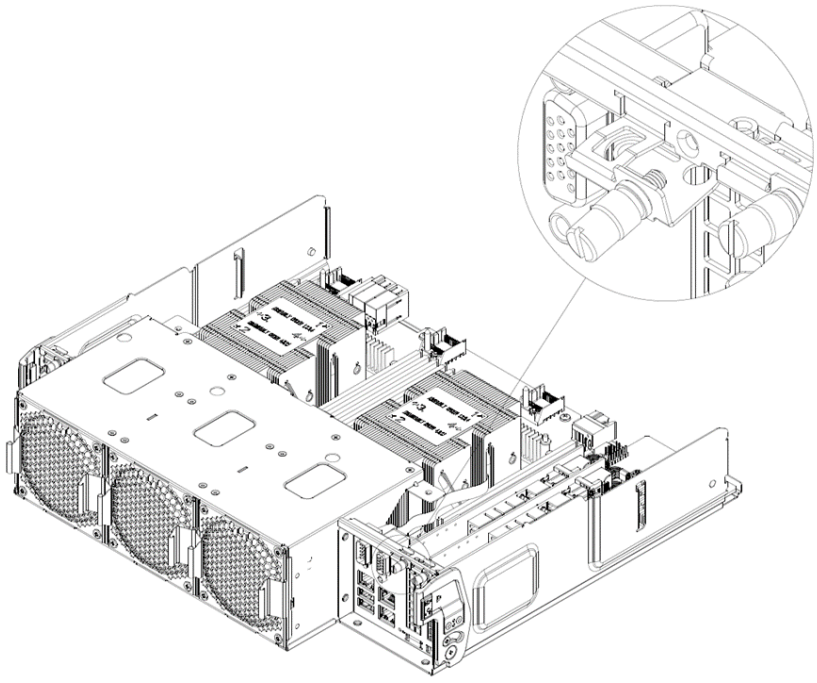
1. Hold the levers and push the lock in. Once it is unlocked, bring the levers down to unseat the node tray.



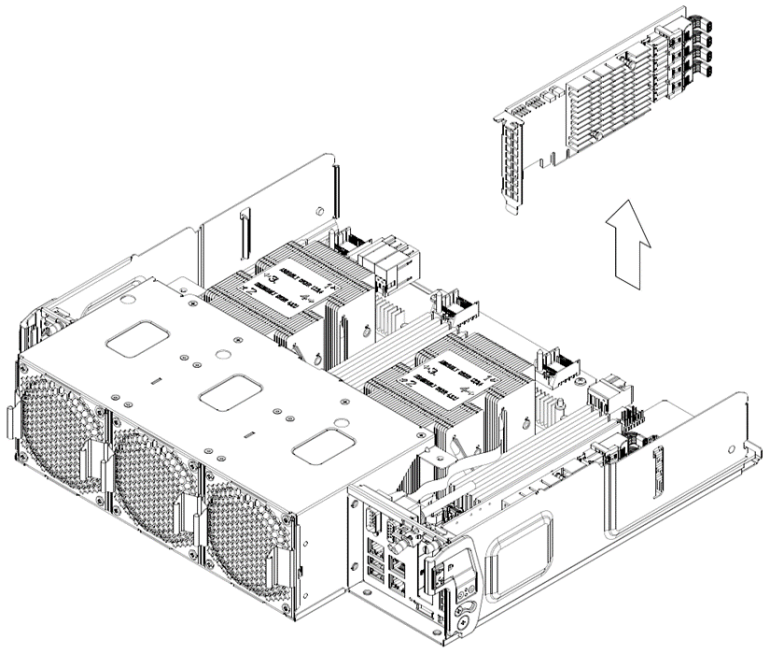
2. Twist the four screws on the top surface of node tray. Once it is unlocked, bring two levers down to release the node cover.



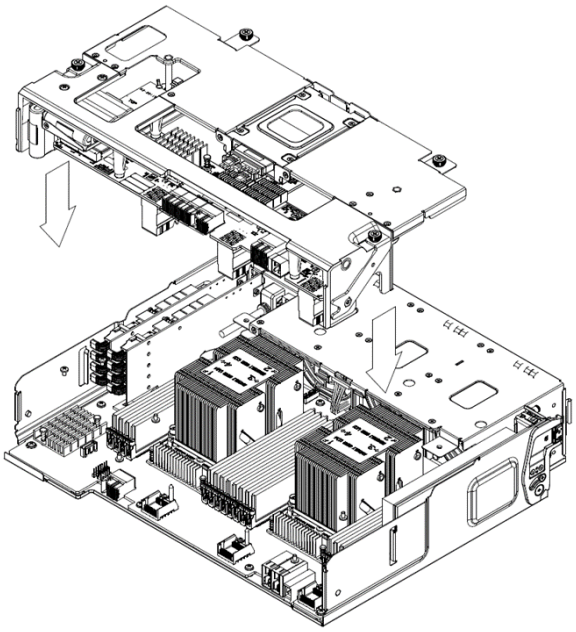
3. Twist the single screw protruding horizontally from the card slot. Once it is unlocked, the screw will remain.



4. Pull the slotted card out vertically.



5. Close the node tray by aligning it vertically and pushing the node cover down.



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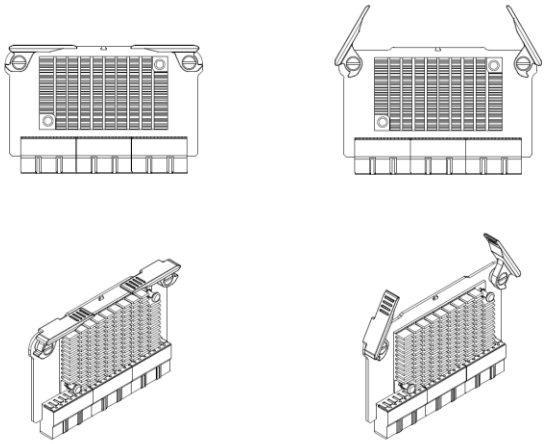
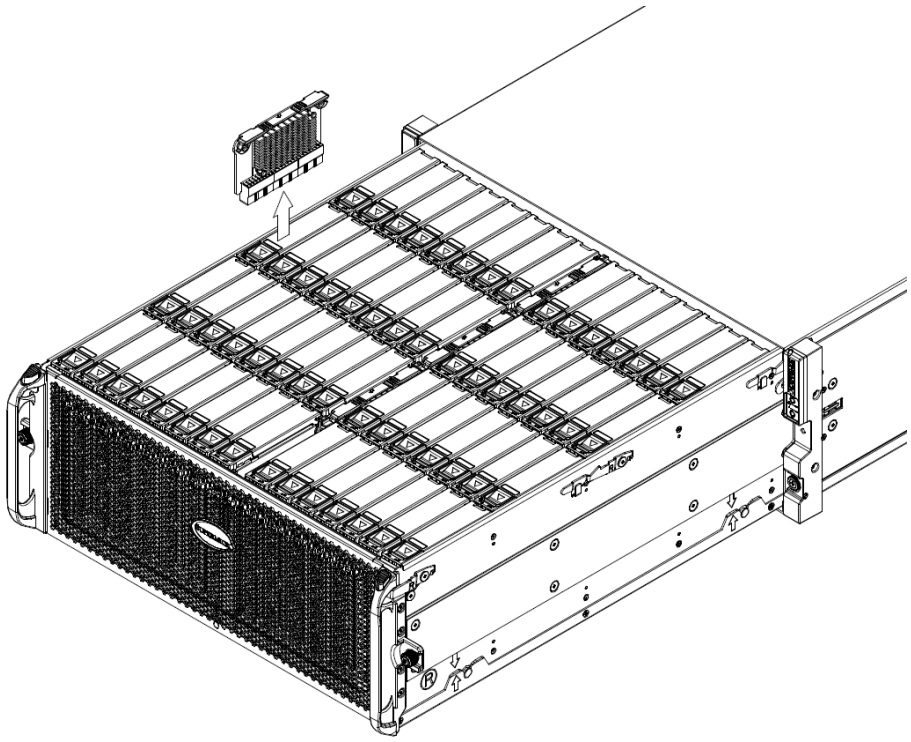
8. Expander Module

Type and number of fastenings: Two (2) latches on each expander module.

Tools required: None.

Procedure: Open both latches to release the expander module from the connector. Pull the expander module out using the latches as handles.





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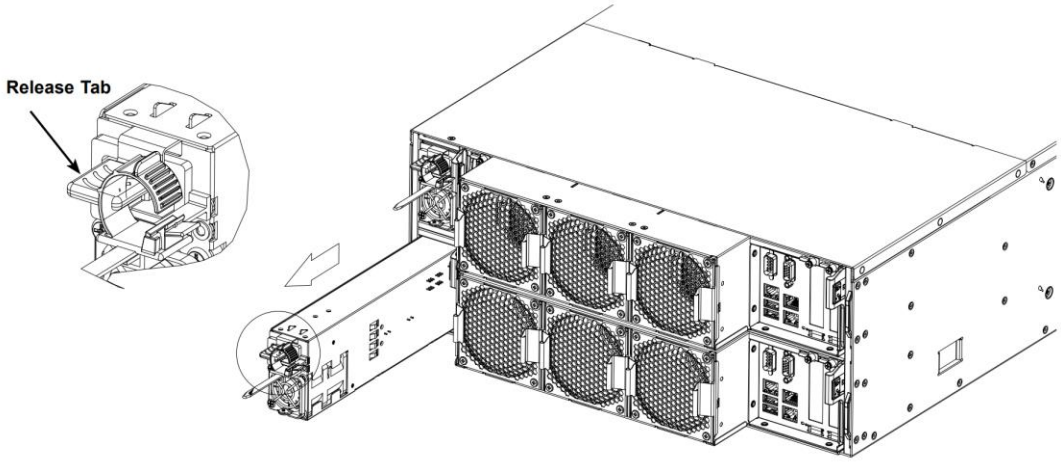
9. Power Supply Module

Type and number of fastenings: One (1) release tab per module.

Tools required: None.

Procedure:

1. Unplug the AC cord from the module.
2. On the back of the module, push the release tab sideways, as illustrated below.
3. Pull the module out using the handle.

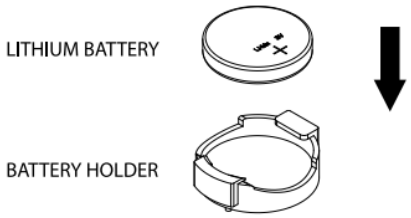


10. Batteries

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure: Push aside the small clamp that covers the edge of the battery. When the battery is released, lift it out of the holder.



11. Fans

Type and number of fastenings: Two (2) latches.

Tools required: None.

Procedure: Push in the tabs to release and pull the fan from the chassis.